

Title	of Change:	NCV70627 Parameters Change (Datasheet Update – Rev.0)					
Prop	osed first ship date:	8 December 2016 or earlier after customer approval					
Conta	act information:	Contact your local ON Semiconductor Sales Office or Javier Alonso <javier.alonso@onsemi.com></javier.alonso@onsemi.com>					
Samples:		Contact your local ON Semiconductor Sales Office					
Addit	tional Reliability Data:	Contact your local ON Semiconductor Sales Office or Javier Alonso <javier.alonso@onsemi.com></javier.alonso@onsemi.com>					
Type of notification:		This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier after customer approval. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact < <u>PCN.Support@onsemi.com</u> >.					
Chan	ge Part Identification:	Affected products will be identified with date code.					
Char	nge category:	Wafer Fab Change Assembly Change Test Change Other _New datasheet version_					
Ch	ange Sub-Category(s): Manufacturing Site Change/. Manufacturing Process Chan	Material Change       Datasheet/Product Doc change         Addition       Product specific change       Shipping/Packaging/Marking         nge       Other:					
Sit	es Affected: All site(s) I not ap	oplicable ON Semiconductor site(s) : External Foundry/Subcon site(s)					
Desci	ription and Purpose						
1)	New package for this produ	uct added (QFN32 5x5, CASE488AM).					
2)	<ol> <li>Absolute Maximum Ratings Supply voltage VBB and hardwired address VHW2: range changed to -0.3V to +40V. The reason to change from 36V to 40V is to improve the test coverage (increasing Vstress level) as the technology is able to withstand that voltage.</li> </ol>						
3)	<ul> <li>Tj - operating junction temperature range changed to <u>parametric</u> operating junction temperature and <u>functional</u> operating junction temperature.</li> <li>Original operating junction temperature was in range from -40 to +165 °C</li> <li><u>Parametric</u> operating junction temperature is now in range from -40 to +145 °C</li> <li><u>Functional</u> operating junction temperature is now in range from -40 to +160 °C (corrected value; to be compatible with other stepper driver chips)</li> </ul>						
4)	<ul> <li>ROjp – thermal resistance, junction to exposed pad changed.</li> <li>Original value was 0.95 K/W but since chip contains non-conductive die attach following values are correct:</li> <li>For <u>SSOP</u> package ROjp is 3.3 K/W.</li> <li>For <u>QFN</u> package ROjp is 14 K/W.</li> <li>The reason for change is the correction of that parameter for SSOP and including the one for QFN package.</li> </ul>						
<ul> <li>In the reason for change is the correction of that parameter for SSOP and including the one for QFN package.</li> <li>Idd_lim – current limitation on the Vdd voltage changed from 80mA to 85mA (@VBB=14V, pin shorted to ground).</li> <li>The reason for relaying the parameter is to have Cnk&gt;1.67 and stable yields in production for both packages over the fab process window.</li> </ul>							
5)	Idd_lim – current limitatior The reason for relaxing the	n on the Vdd voltage changed from 80mA to 85mA (@VBB=14V, pin shorted to ground). parameter is to have Cpk>1.67 and stable yields in production for both packages over the fab process window.					



Issue Date: 8 December 2015

#### **Reliability Data Summary: See attached Qualification reports**

To access file attachments on pdf copy of PCN, please be guided by the steps below:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file/s

#### **Electrical Characteristic Summary:**

#### Absolute Maximum Ratings

• Original Datasheet (Table 2, p 3):

Parameter		Min	Max	Unit
V <sub>BB</sub> , VHW2	Supply voltage, hardwired address pin (Note 4)	-0.3	+36 (Note 3)	V

NOTE:

3. For limited time:  $V_{BB}$  <0.5 s, SWI and HW2 pins <1.0 s.

4. Maximum allowed voltage between two device pins is 60 V.

#### • Updated Datasheet (Table 2, p 2):

Parameter		Min	Max	Unit
V <sub>BB</sub> , VHW2	Supply voltage, hardwired address pin (Note 4)	-0.3	+40 (Note 3)	V

NOTE:

3. For limited time: V<sub>BB</sub> <0.5 s, SWI and HW2 pins <1.0 s.

4. Maximum allowed voltage between two device pins is 60 V.

#### **Operating Ranges**

• Original Datasheet (Table 3, p3) :

### Table 3. OPERATING RANGES

Parameter		Min	Max	Unit
V <sub>BB</sub>	Supply voltage	+5.5	+29	V
TJ	Operating junction temperature range (Note 5)	-40	+165	°C

NOTE:

5. The circuit functionality is not guaranteed outside the Operating junction temperature range.

A mission profile describes the application specific conditions such as, but not limited to, the cumulative operating conditions over life time, the system power dissipation, the system's environmental conditions, the thermal design of the customer's system, the modes, in which the device is operated by the customer, etc.

### • Updated Datasheet (Table 3, p2) :

#### Table 3. OPERATING RANGES

Parameter		Min	Max	Unit
V <sub>BB</sub>	Supply voltage	+5.5	+29	V
T <sub>JP</sub>	Parametric Operating junction temperature range (Note 8)	-40	+145	°C
T <sub>JF</sub>	Functional Operating junction temperature range (Note 9)	-40	+160	°C

NOTE:

8. The parametric characteristics of the circuit are not guaranteed outside the parametric operating junction temperature range.

9. The maximum functional operating temperature range can be limited by thermal shutdown Ttsd.



## Thermal Resistance

<ul> <li>Original Datasheet (Table</li> </ul>	5,	p6):	
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Package	Rth	Rth	Rth
	Junction-to-Leads and	Junction-to-Ambient	Junction–to–Ambient
	Exposed Pad – Rthjp	Rthja (1S0P)	Rthja (2S2P)
SSOP-36EP	0,95	60	30

# • Updated Datasheet (Table 6, p5) :

Table 6. THERMAL RESISTANCE							
Characteristics	Package	Symbol	Min	Тур	Max	Unit	
Thermal Resistance, Junction-to-Exposed Pad (Note 10)	SSOP-36	$R_{\theta JP}$	-	3.3	-	K/W	
Thermal Resistance, Junction-to-Exposed Pad (Note 10)     QFN32     R <sub>0JP</sub> -     14     -     K/W						K/W	
10 Also includes typical solder thickness under the Exposed Pad (E	P)						

## **DC Parameters**

• Original Datasheet (Table 6, p8) :

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I <sub>ddLim</sub>	Current limitation	Current limitation Pin shorted to ground V <sub>BB</sub> = 14 V		80	mA		
• Updated Datasheet (Table 7, p7) :							
l <sub>ddLim</sub>	Current limitation	Pin shorted to ground V <sub>BB</sub> = 14 V			85	mA	
List of affected S	tandard Parts:						
	Part Number Qualification Vehicle						
NCV70627DQ001G			NA				
NCV70627DQ001R2G				NA			
	NCV70627MW002R2G			NA			